

## SN74LVCH16245A 16-bit Bus Transceiver With 3-state Outputs

### 1 Features

- Member of the Texas Instruments Widebus™ Family
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 4 ns at 3.3 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  $>2$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V  $V_{CC}$ )
- $I_{off}$  Supports Live Insertion, Partial-Power-Down Mode, and Back-Drive Protection
- Bus Hold on Data Inputs Eliminates the Need for External Pullup or Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

### 2 Applications

- Electronic Points of Sale
- Test and Measurement
- Wearable Health and Fitness Devices
- Tablets

### 3 Description

This 16-bit (dual-octal) noninverting bus transceiver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation. The SN74LVCH16245A device is designed for asynchronous communication between data buses.

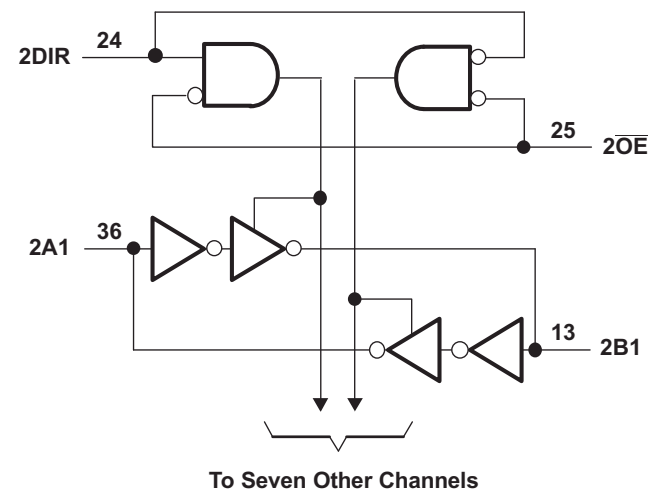
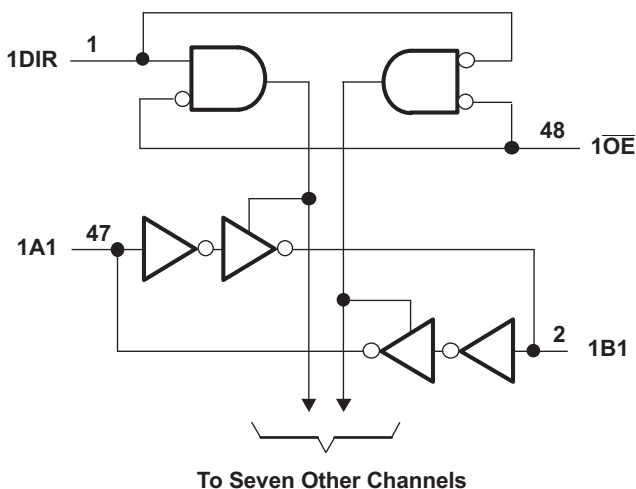
This device can be used as two 8-bit transceivers or one 16-bit transceiver. Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LVCH16245A	TSSOP (48)	12.50 mm x 6.10 mm
	TVSOP (48)	9.70 mm x 4.40 mm
	SSOP (48)	15.88 mm x 7.49 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### 4 Simplified Schematic



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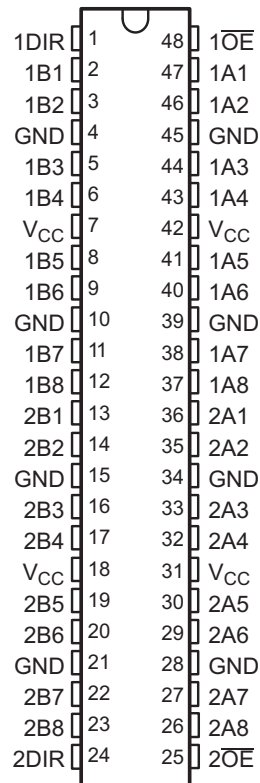
## 5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision B (August 2006) to Revision C</b>	<b>Page</b>
• Updated document to new TI data sheet format .....	1
• Removed Ordering Information table .....	1
• Updated $I_{off}$ Feature bullet .....	1
• Added Applications .....	1
• Added Device Information table .....	1
• Added Handling Ratings table .....	6
• Changed MAX ambient temperature to 125°C .....	7
• Added Thermal Information table .....	7
• Updated $t_{sk(o)}$ values in Switching Characteristics table .....	9
• Added Typical Characteristics .....	9

## 6 Pin Configuration and Functions

DGG, DGV, OR DL PACKAGE  
(TOP VIEW)



**Pin Functions**

PIN		I/O	DESCRIPTION
NO.	NAME		
1	1DIR	I	Direction pin 1
2	1B1	I/O	1B1 input or output
3	1B2	I/O	1B2 input or output
4	GND	—	Ground pin
5	1B3	I/O	1B3 input or output
6	1B4	I/O	1B4 input or output
7	VCC	—	Power pin
8	1B5	I/O	1B5 input or output
9	1B6	I/O	1B6 input or output
10	GND	—	Ground pin
11	1B7	I/O	1B7 input or output
12	1B8	I/O	1B8 input or output
13	2B1	I/O	2B1 input or output
14	2B2	I/O	2B2 input or output
15	GND	—	Ground pin
16	2B3	I/O	2B3 input or output
17	2B4	I/O	2B4 input or output
18	VCC	—	Power pin
19	2B5	I/O	2B5 input or output
20	2B6	I/O	2B6 input or output

**Pin Functions (continued)**

PIN		I/O	DESCRIPTION
NO.	NAME		
21	GND	—	Ground pin
22	2B7	I/O	2B7 input or output
23	2B8	I/O	2B8 input or output
24	2DIR	—	Direction pin 2
25	2 $\overline{\text{OE}}$	I	Output Enable 2
26	2A8	I/O	2A8 input or output
27	2A7	I/O	2A7 input or output
28	GND	—	Ground pin
29	2A6	I/O	2A6 input or output
30	2A5	I/O	2A5 input or output
31	VCC	—	Power pin
32	2A4	I/O	2A4 input or output
33	2A3	I/O	2A3 input or output
34	GND	—	Ground pin
35	2A2	I/O	2A2 input or output
36	2A1	I/O	2A1 input or output
37	1A8	I/O	1A8 input or output
38	1A7	I/O	1A7 input or output
39	GND	—	Ground pin
40	1A6	I/O	1A6 input or output
41	1A5	I/O	1A5 input or output
42	VCC	—	Power pin
43	1A4	I/O	1A4 input or output
44	1A3	I/O	1A3 input or output
45	GND	—	Ground pin
46	1A2	I/O	1A2 input or output
47	1A1	I/O	1A1 input or output
48	1 $\overline{\text{OE}}$	I	Output Enable 1

QGL OR ZQL PACKAGE  
(TOP VIEW)

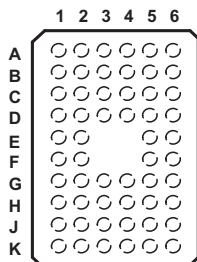


Table 1. Pin Assignments<sup>(1)</sup> (56-Ball GQL or ZQL Package)

	1	2	3	4	5	6
A	1DIR	NC	NC	NC	NC	1 $\overline{OE}$
B	1B2	1B1	GND	GND	1A1	1A2
C	1B4	1B3	V <sub>CC</sub>	V <sub>CC</sub>	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
H	2B5	2B6	V <sub>CC</sub>	V <sub>CC</sub>	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 $\overline{OE}$

(1) NC – No internal connection

GRD OR ZRD PACKAGE  
(TOP VIEW)

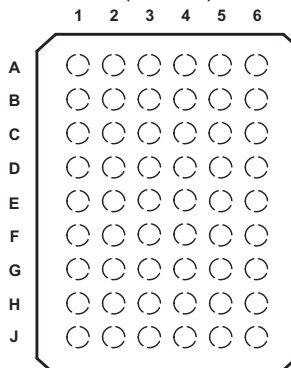


Table 2. Pin Assignments<sup>(1)</sup> (54-Ball GRD or ZRD Package)

	1	2	3	4	5	6
A	1B1	NC	1DIR	1 $\overline{OE}$	NC	1A1
B	1B3	1B2	NC	NC	1A2	1A3
C	1B5	1B4	V <sub>CC</sub>	V <sub>CC</sub>	1A4	1A5
D	1B7	1B6	GND	GND	1A6	1A7
E	2B1	1B8	GND	GND	1A8	2A1
F	2B3	2B2	GND	GND	2A2	2A3
G	2B5	2B4	V <sub>CC</sub>	V <sub>CC</sub>	2A4	2A5
H	2B7	2B6	NC	NC	2A6	2A7
J	2B8	NC	2DIR	2 $\overline{OE}$	NC	2A8

(1) NC – No internal connection

## 7 Specifications

### 7.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	6.5	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	6.5	V
V <sub>O</sub>	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50 mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50 mA
I <sub>O</sub>	Continuous output current			±50 mA
Continuous current through each V <sub>CC</sub> or GND				±100 mA

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

### 7.2 Handling Ratings

		MIN	MAX	UNIT	
T <sub>stg</sub>	Storage temperature range	-65	150	°C	
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	0	2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	0	1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V	2		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V	0.8		
V <sub>I</sub>	Input voltage		0	5.5	V
V <sub>O</sub>	Output voltage	High or low state	0	V <sub>CC</sub>	V
		3-state	0	5.5	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V		−4	mA
		V <sub>CC</sub> = 2.3 V		−8	
		V <sub>CC</sub> = 2.7 V		−12	
		V <sub>CC</sub> = 3 V		−24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V		4	mA
		V <sub>CC</sub> = 2.3 V		8	
		V <sub>CC</sub> = 2.7 V		12	
		V <sub>CC</sub> = 3 V		24	
Δt/Δv	Input transition rise and fall rate			5	ns/V
T <sub>A</sub>	Operating free-air temperature		−40	125	°C

(1) All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		DGG	DGV	DL	UNIT
		48 PINS	48 PINS	48 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	67.1	80.2	70.6	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	19.9	32.7	36.8	
R <sub>θJB</sub>	Junction-to-board thermal resistance	34.2	43.5	43.1	
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	1.8	4.7	13.9	
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	33.9	42.9	42.6	
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	n/a	n/a	n/a	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V
		I <sub>OH</sub> = -4 mA	1.65 V	1.2			
		I <sub>OH</sub> = -8 mA	2.3 V	1.7			
		I <sub>OH</sub> = -12 mA	2.7 V	2.2			
			3 V	2.4			
		I <sub>OH</sub> = -24 mA	3 V	2.2			
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2	V
		I <sub>OL</sub> = 4 mA	1.65 V			0.45	
		I <sub>OL</sub> = 8 mA	2.3 V			0.7	
		I <sub>OL</sub> = 12 mA	2.7 V			0.4	
		I <sub>OL</sub> = 24 mA	3 V			0.55	
I <sub>I</sub>	Control inputs	V <sub>I</sub> = 0 to 5.5 V	3.6 V			±5	μA
I <sub>I(hold)</sub>	A or B port	V <sub>I</sub> = 0.58 V	1.65 V	15		±500	μA
		V <sub>I</sub> = 1.07 V		-15			
		V <sub>I</sub> = 0.7 V	2.3 V	45			
		V <sub>I</sub> = 1.7 V		-45			
		V <sub>I</sub> = 0.8 V	3 V	75			
		V <sub>I</sub> = 2 V		-75			
		V <sub>I</sub> = 0 to 3.6 V <sup>(2)</sup>	3.6 V				
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0			±10	μA
I <sub>OZ</sub> <sup>(3)</sup>		V <sub>O</sub> = 0 V or (V <sub>CC</sub> to 5.5 V)	2.3 V to 3.6 V			±5	μA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	I <sub>O</sub> = 0		20	μA
		3.6 V ≤ V <sub>I</sub> ≤ 5.5 V <sup>(4)</sup>				20	
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500	μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V			5	pF
C <sub>io</sub>	A or B port	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V			7.5	pF

 (1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This is the bus-hold maximum dynamic current required to switch the input from one state to another.

 (3) For the total leakage current in an I/O port, consult the I<sub>I(hold)</sub> specification for the input voltage condition 0 V < V<sub>I</sub> < V<sub>CC</sub>, and the I<sub>OZ</sub> specification for the input voltage conditions V<sub>I</sub> = 0 V or V<sub>I</sub> = V<sub>CC</sub> to 5.5 V. The bus-hold current, at input voltage greater than V<sub>CC</sub>, is negligible.

(4) This applies in the disabled state only.



### 7.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A or B	B or A	1.5	7.1	1	4.5	1	4.7	1	4	ns
$t_{en}$	$\overline{OE}$	A or B	1.5	8.9	1	5.6	1.5	6.7	1.5	5.5	ns
$t_{dis}$	$\overline{OE}$	A or B	1.5	11.9	1	6.8	1.5	7.1	1.5	6.6	ns
$t_{sk(o)}$				1		1		1		1	ns

### 7.7 Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
				TYP	TYP	TYP	
$C_{pd}$	Power dissipation capacitance per transceiver	Outputs enabled	$f = 10\text{ MHz}$	36	36	40	pF
		Outputs disabled		3	3	4	

### 7.8 Typical Characteristics

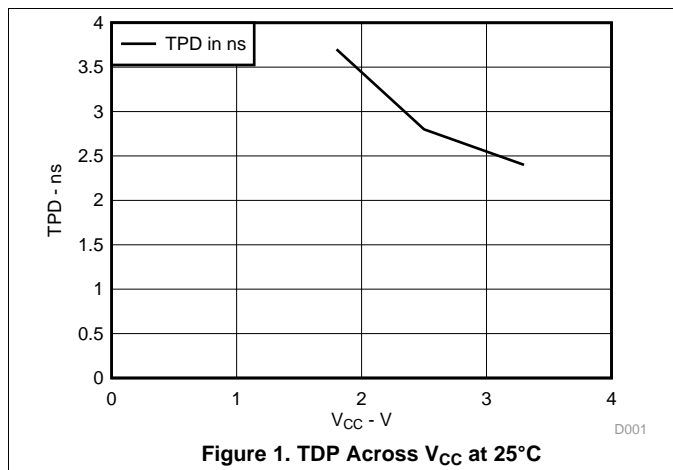


Figure 1. TDP Across V<sub>CC</sub> at 25°C

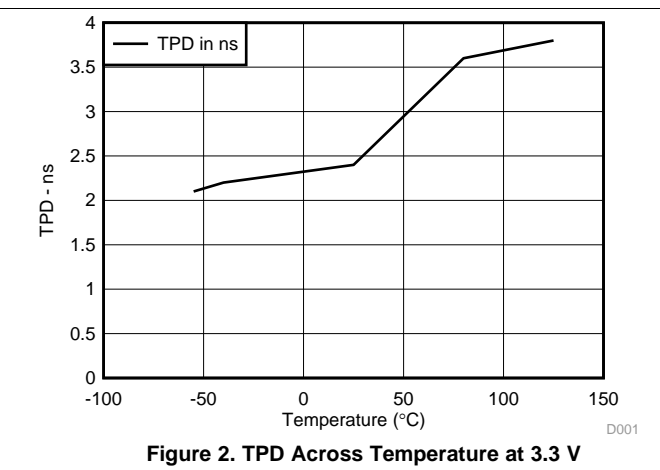
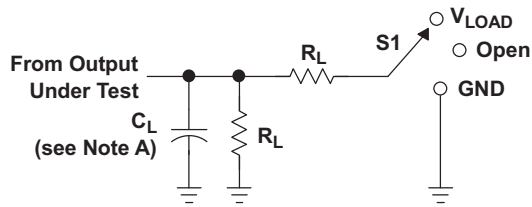


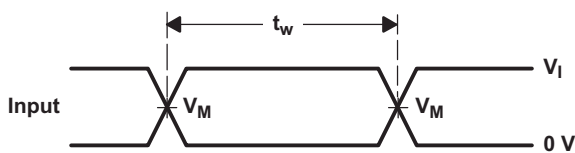
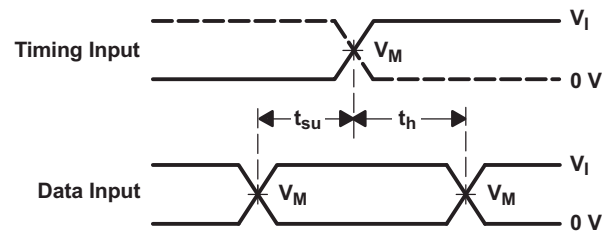
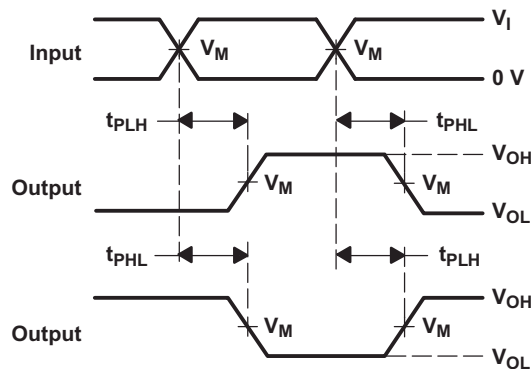
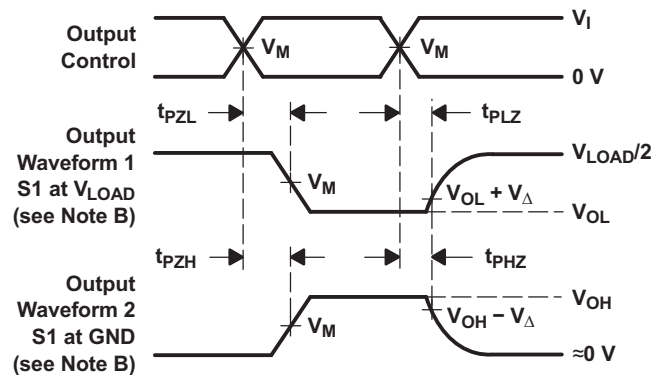
Figure 2. TDP Across Temperature at 3.3 V

## 8 Parameter Measurement Information


**LOAD CIRCUIT**

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V


**VOLTAGE WAVEFORMS  
PULSE DURATION**

**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**

**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**

**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

**Figure 3. Load Circuit and Voltage Waveforms**

## 9 Detailed Description

### 9.1 Overview

The SN74LVCH16245A device is designed for asynchronous communication between data buses. The logic levels of the direction-control (DIR) input and the output-enable ( $\overline{OE}$ ) input activate either the B-port outputs or the A-port outputs or place both output ports into the high-impedance mode. The device transmits data from the A bus to the B bus when the B-port outputs are activated, and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports always is active and must have a logic high or low level applied to prevent excess  $I_{CC}$  and  $I_{CCZ}$ .

Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended. The bus-hold circuitry is part of the input circuit and is not disabled by  $\overline{OE}$  or DIR.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V and 5-V system environment.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, thus preventing damaging current backflow through the device when it is powered down.

### 9.2 Functional Block Diagram

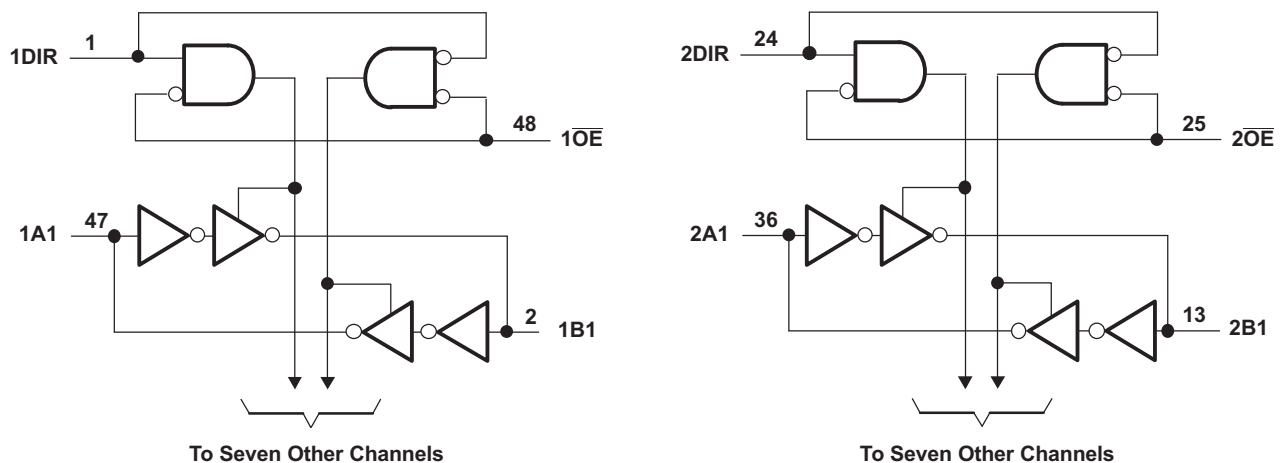


Figure 4. Logic Diagram (Positive Logic)

### 9.3 Feature Description

- Wide operating voltage range
  - Operates from 1.65 V to 3.6 V
- Allows down voltage translation
  - Inputs accept voltages to 5.5 V
- $I_{off}$  feature
  - Allows voltages on the inputs and outputs when  $V_{CC}$  is 0 V

### 9.4 Device Functional Modes

**Table 3. Function Table<sup>(1)</sup>  
(Each 8-bit Section)**

CONTROL INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

(1) Input circuits of the data I/Os always are active.

## 10 Application and Implementation

### 10.1 Application Information

The SN74LVCH16245A device is a 16-bit bidirectional transceiver. This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses are effectively isolated. The device has 5.5 V tolerant inputs at any valid  $V_{CC}$ . This allows it to be used in multi-power systems, and it can be used for down translation.

### 10.2 Typical Application

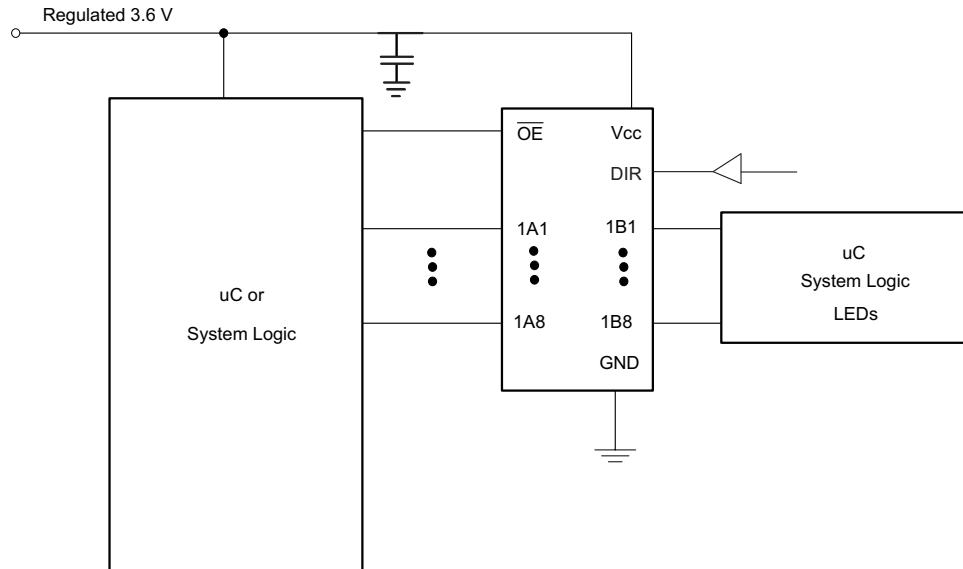


Figure 5. Typical Application Diagram

#### 10.2.1 Design Requirements

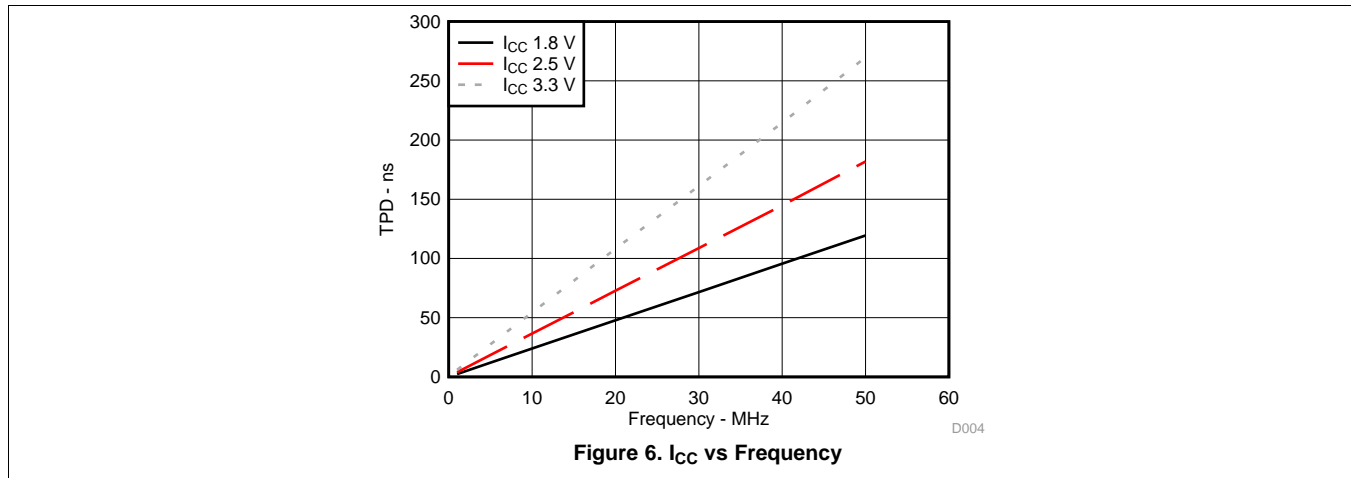
This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads; therefore, routing and load conditions should be considered to prevent ringing.

#### 10.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - Rise time and fall time specs: See  $(\Delta t/\Delta V)$  in the [Recommended Operating Conditions](#) table.
  - Specified high and low levels: See ( $V_{IH}$  and  $V_{IL}$ ) in the [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend Output Conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

## Typical Application (continued)

### 10.2.3 Application Curves



## 11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Recommended Operating Conditions](#) table.

Each V<sub>CC</sub> pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 µf is recommended; if there are multiple V<sub>CC</sub> pins, then 0.01 µf or 0.022 µf is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 µf and a 1 µf are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

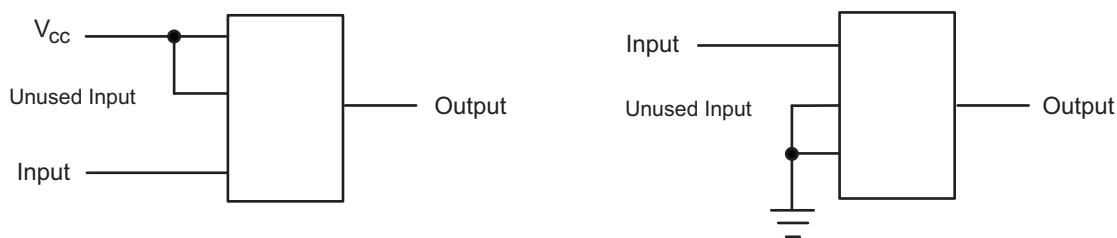
## 12 Layout

### 12.1 Layout Guidelines

When using multiple-bit logic devices, inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. [Figure 7](#) specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V<sub>CC</sub>, whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the output section of the part when asserted. This will not disable the input section of the I/Os, so they cannot float when disabled.

### 12.2 Layout Example



**Figure 7. Layout Diagram**

## 13 Device and Documentation Support

### 13.1 Trademarks

Widebus is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74LVCH16245ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCH16245A	<a href="#">Samples</a>
74LVCH16245ADLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCH16245A	<a href="#">Samples</a>
SN74LVCH16245ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCH16245A	<a href="#">Samples</a>
SN74LVCH16245ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LDH245A	<a href="#">Samples</a>
SN74LVCH16245ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCH16245A	<a href="#">Samples</a>
SN74LVCH16245ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCH16245A	<a href="#">Samples</a>
SN74LVCH16245ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVCH16245A	<a href="#">Samples</a>
SN74LVCH16245AGQLR	OBSOLETE	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85	LDH245A	
SN74LVCH16245AGRDR	OBSOLETE	BGA MICROSTAR JUNIOR	GRD	54		TBD	Call TI	Call TI	-40 to 85		
SN74LVCH16245AZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LDH245A	<a href="#">Samples</a>
SN74LVCH16245AZRDR	ACTIVE	BGA MICROSTAR JUNIOR	ZRD	54	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LDH245A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.



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**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVCH16245ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74LVCH16245ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74LVCH16245AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74LVCH16245AZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	330.0	16.4	5.8	8.3	1.55	8.0	16.0	Q1

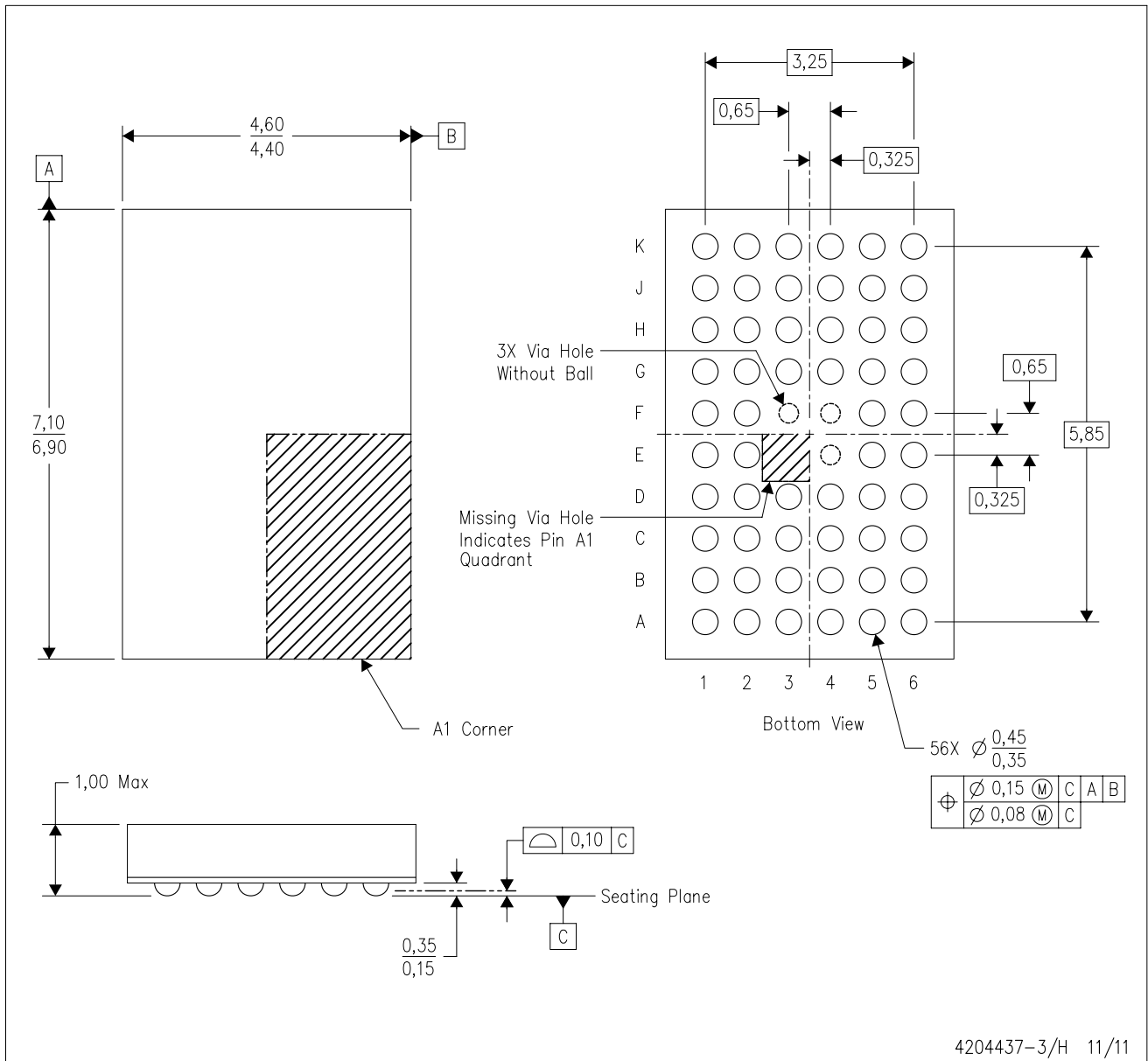
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVCH16245ADGVR	TVSOP	DGV	48	2000	367.0	367.0	38.0
SN74LVCH16245ADLR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74LVCH16245AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	336.6	336.6	28.6
SN74LVCH16245AZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	336.6	336.6	28.6

ZQL (R-PBGA-N56)

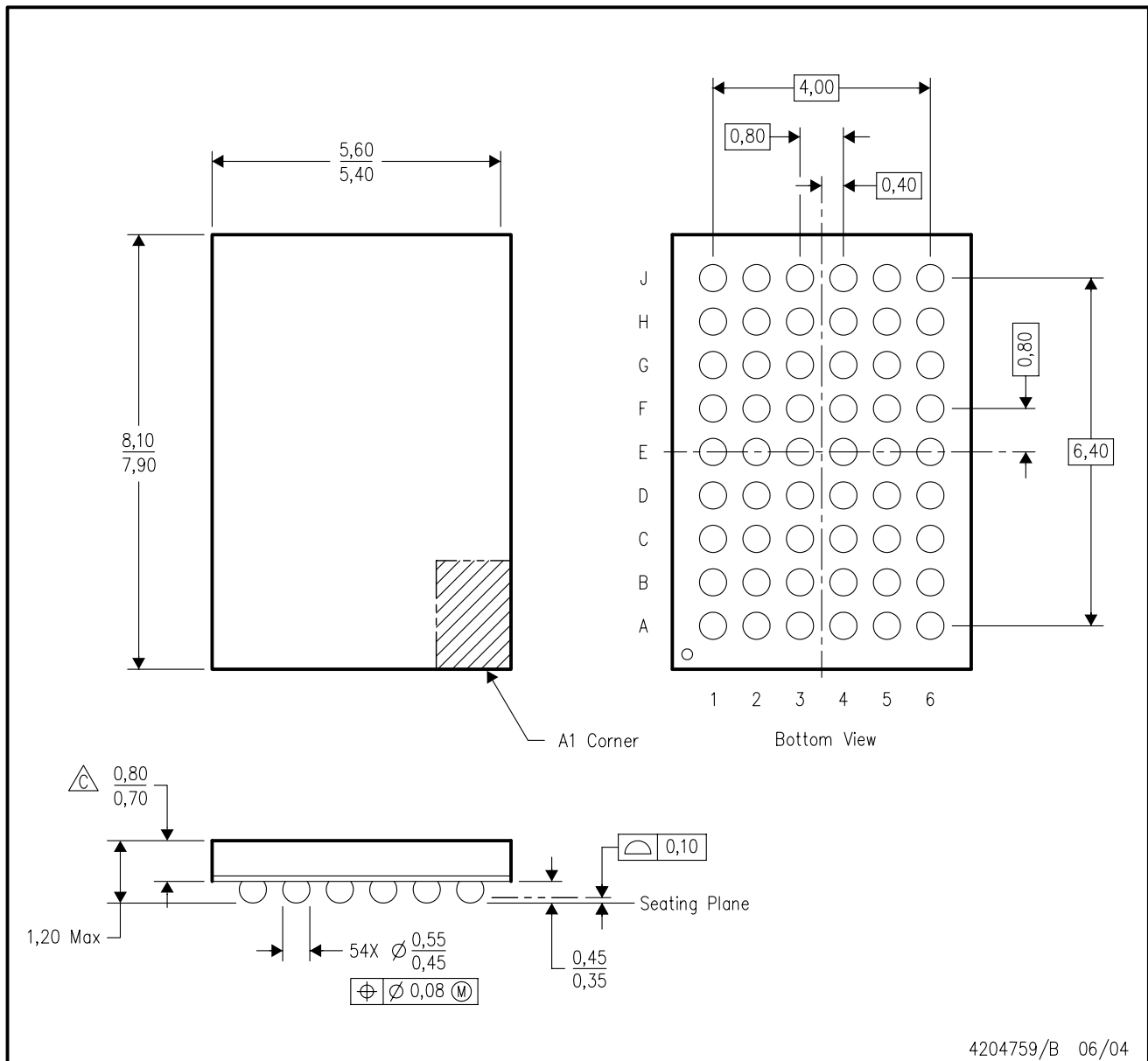
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-285 variation BA-2.
  - D. This package is Pb-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

GRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY




- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MO-205 variation DD.
  - D. This package is tin-lead (SnPb). Refer to the 54 ZRD package (drawing 4204760) for lead-free.

ZRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  -  Falls within JEDEC MO-205 variation DD.
  - D. This package is lead-free. Refer to the 54 GRD package (drawing 4204759) for tin-lead (SnPb).

# MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE

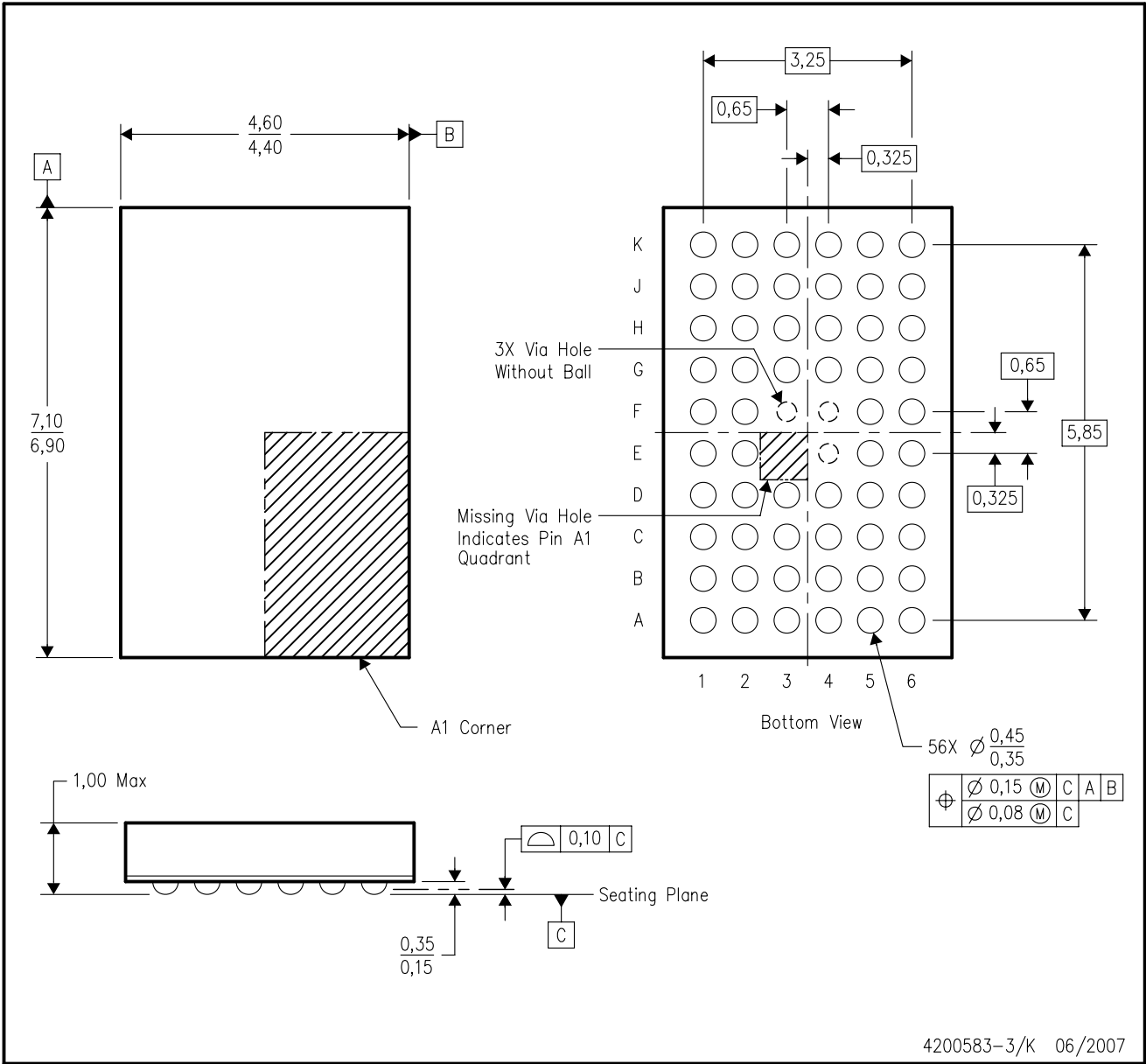


- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



- NOTES:
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  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-285 variation BA-2.
  - D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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